

IN THE CLAIMS

1. (Currently Amended) A wiring board comprising:
a core substrate defining an opening;
an electronic component;
an embedding resin having a dielectric constant of less than or equal to about 5 and $\tan\delta$ of less than or equal to about 0.08; and
a substrate in which a build-up layer formed by laminating an insulating and a wiring layer in alternate fashion is formed,
wherein, said electronic component is embedded in the opening by said embedding resin,
~~and~~
wherein the substrate in which the build-up layer is formed is disposed across the opening and in contiguous contact with the core substrate and the embedding resin,
wherein the electronic component includes an electrode, and
wherein a distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 100 μm .
2. (Original) The wiring board according to claim 1, wherein said embedding resin comprises carbon black in an amount of less than or equal to about 1.4 mass%.
3. (Original) The wiring board according to claim 1, wherein said embedding resin comprises a thermosetting resin as a resin component and at least one inorganic filler.

4. (Original) The wiring board according to claim 3, wherein said thermosetting resin is at least one of a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, or a cresol-novolak-type epoxy resin.
5. (Original) The wiring board according to claim 1, wherein said embedding resin assumes a color having a base color tone of black, blue, green, red, orange, yellow, or violet.
6. (Canceled)
7. (Canceled)
8. (Canceled)
9. (Currently Amended) The wiring board according to claim ~~[[8]]~~ 1, wherein the distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 50 μm .
10. (Previously Presented) The wiring board according to claim 9, wherein the distance from the electrode to the wiring layer of the substrate in which the build-up layer formed is less than or equal to 30 μm .
11. (Previously Presented) The wiring board according to claim 1, wherein via holes are formed in the insulating layer.